

CD74HC240, CD74HCT240, CD74HC241, CD74HCT241, CD74HC244, CD74HCT244

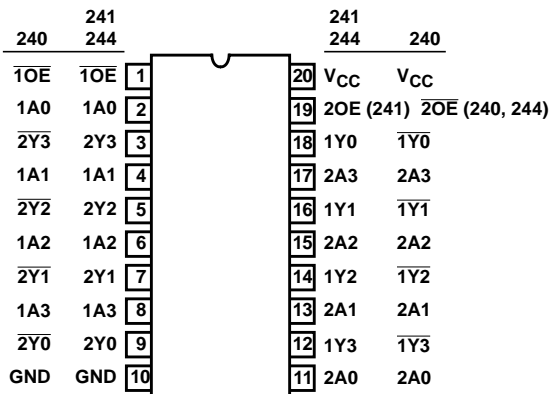
High Speed CMOS Logic Octal Buffer/Line Drivers, Three-State

Features

- CD74HC/HCT240 Inverting
- CD74HC/HCT241 Non-Inverting
- CD74HC/HCT244 Non-Inverting
- Typical Propagation Delay = 8ns at $V_{CC} = 5V$,
 $C_L = 15pF$, $T_A = 25^\circ C$ for HC240
- Three-State Outputs
- Buffered Inputs
- High-Current Bus Driver Outputs
- Fanout (Over Temperature Range)
 - Standard Outputs 10 LSTTL Loads
 - Bus Driver Outputs 15 LSTTL Loads
- Wide Operating Temperature Range . . . $-55^\circ C$ to $125^\circ C$
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
 - 2V to 6V Operation
 - High Noise Immunity: $N_{IL} = 30\%$, $N_{IH} = 30\%$ of V_{CC} at $V_{CC} = 5V$
- HCT Types
 - 4.5V to 5.5V Operation
 - Direct LSTTL Input Logic Compatibility, $V_{IL} = 0.8V$ (Max), $V_{IH} = 2V$ (Min)
 - CMOS Input Compatibility, $I_I \leq 1\mu A$ at V_{OL} , V_{OH}

Pinout

CD74HC240, CD74HCT240, CD74HC241, CD74HCT241,
CD74HC244, CD74HCT244
(PDIP, SOIC)
TOP VIEW



CD74HC240, CD74HCT240, CD74HC241, CD74HCT241, CD74HC244, CD74HCT244

Description

The Harris CD74HC240 and CD74HCT240 are inverting three-state buffers having two active-low output enables. The Harris CD74HC241, CD74HCT241, CD74HC244 and CD74HCT244 are non-inverting three-state buffers that differ only in that the 241 has one active-high and one active-low output enable, and the 244 has two active-low output enables. All three types have identical pinouts.

Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE	PKG. NO.
CD74HC240E	-55 to 125	20 Ld PDIP	E20.3
CD74HCT240E	-55 to 125	20 Ld PDIP	E20.3
CD74HC241E	-55 to 125	20 Ld PDIP	E20.3
CD74HCT241E	-55 to 125	20 Ld PDIP	E20.3
CD74HC244E	-55 to 125	20 Ld PDIP	E20.3

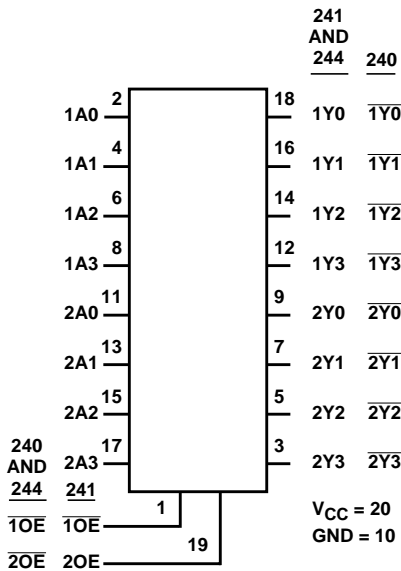
Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE	PKG. NO.
CD74HCT244E	-55 to 125	20 Ld PDIP	E20.3
CD74HC240M	-55 to 125	20 Ld SOIC	M20.3
CD74HCT241M	-55 to 125	20 Ld SOIC	M20.3
CD74HCT240M	-55 to 125	20 Ld SOIC	M20.3
CD74HC244M	-55 to 125	20 Ld SOIC	M20.3
CD74HCT244M	-55 to 125	20 Ld SOIC	M20.3

NOTES:

1. When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.
2. Wafer and die for this part number is available which meets all electrical specifications. Please contact your local sales office or Harris customer service for ordering information.

Functional Diagram



CD74HC240, CD74HCT240, CD74HC241, CD74HCT241, CD74HC244, CD74HCT244

Absolute Maximum Ratings

DC Supply Voltage, V_{CC}	-0.5V to 7V
DC Input Diode Current, I_{IK}	
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$	$\pm 20mA$
DC Output Diode Current, I_{OK}	
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$	$\pm 20mA$
DC Drain Current, per Output, I_O	
For $-0.5V < V_O < V_{CC} + 0.5V$	$\pm 35mA$
DC Output Source or Sink Current per Output Pin, I_O	
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$	$\pm 25mA$
DC V_{CC} or Ground Current, I_{CC}	$\pm 70mA$

Thermal Information

Thermal Resistance (Typical, Note 3)	θ_{JA} ($^{\circ}C/W$)
PDIP Package	125
SOIC Package	120
Maximum Junction Temperature	150 $^{\circ}C$
Maximum Storage Temperature Range	-65 $^{\circ}C$ to 150 $^{\circ}C$
Maximum Lead Temperature (Soldering 10s)	300 $^{\circ}C$ (SOIC - Lead Tips Only)

Operating Conditions

Temperature Range (T_A)	-55 $^{\circ}C$ to 125 $^{\circ}C$
Supply Voltage Range, V_{CC}	
HC Types2V to 6V
HCT Types	4.5V to 5.5V
DC Input or Output Voltage, V_I, V_O	0V to V_{CC}
Input Rise and Fall Time	
2V	1000ns (Max)
4.5V	500ns (Max)
6V	400ns (Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

- θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		V_{CC} (V)	25 $^{\circ}C$			-40 $^{\circ}C$ TO 85 $^{\circ}C$		-55 $^{\circ}C$ TO 125 $^{\circ}C$		UNITS
		V_I (V)	I_O (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES												
High Level Input Voltage	V_{IH}	-	-	2	1.5	-	-	1.5	-	1.5	-	V
				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input Voltage	V_{IL}	-	-	2	-	-	0.5	-	0.5	-	0.5	V
				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output Voltage CMOS Loads	V_{OH}	V_{IH} or V_{IL}	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output Voltage TTL Loads	V_{OH}	V_{IH} or V_{IL}	-6	4.5	3.98	-	-	3.84	-	3.7	-	V
			-7.8	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	V_{OL}	V_{IH} or V_{IL}	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads	V_{OL}	V_{IH} or V_{IL}	6	4.5	-	-	0.26	-	0.33	-	0.4	V
			7.8	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I_I	V_{CC} or GND	-	6	-	-	± 0.1	-	± 1	-	± 1	μA
Quiescent Device Current	I_{CC}	V_{CC} or GND	0	6	-	-	8	-	80	-	160	μA

CD74HC240, CD74HCT240, CD74HC241, CD74HCT241, CD74HC244, CD74HCT244

DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS		V _{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V _I (V)	I _O (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Three-State Leakage Current	I _{OZ}	V _{IL} or V _{IH}	-	6	-	-	±0.5	-	±0.5	-	±10	μA
HCT TYPES												
High Level Input Voltage	V _{IH}	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V _{IL}	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V _{OH}	V _{IH} or V _{IL}	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-6	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V _{OL}	V _{IH} or V _{IL}	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			6	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I _I	V _{CC} to GND	0	5.5	-	-	±0.1	-	±1	-	±1	μA
Quiescent Device Current	I _{CC}	V _{CC} or GND	0	5.5	-	-	8	-	80	-	160	μA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load (Note 4)	ΔI _{CC}	V _{CC} -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	μA
Three-State Leakage Current	I _{OZ}	V _{IL} or V _{IH}	-	5.5	-	-	±0.5	-	±5	-	±10	μA

NOTE:

4. For dual-supply systems theoretical worst case (V_I = 2.4V, V_{CC} = 5.5V) specification is 1.8mA.

HCT Input Loading Table

INPUT	UNIT LOADS
CD74HCT240	
nA0-A3	1.5
$\overline{1OE}$	0.7
$\overline{2OE}$	0.7
CD74HCT241	
nA0-A3	0.7
$\overline{1OE}$	0.7
2OE	1.5
CD74HCT244	
nA0-A3	0.7
$\overline{1OE}$	0.7
$\overline{2OE}$	0.7

NOTE: Unit Load is ΔI_{CC} limit specified in DC Electrical Specifications table, e.g., 360μA max at 25°C.

CD74HC240, CD74HCT240, CD74HC241, CD74HCT241, CD74HC244, CD74HCT244

Switching Specifications $C_L = 50\text{pF}$, Input $t_r, t_f = 6\text{ns}$

PARAMETER	SYMBOL	TEST CONDITIONS	V _{CC} (V)	25°C			-40°C TO 85°C			-55°C TO 125°C			UNITS
				MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
HC TYPES													
Propagation Delay Data to Outputs HC240	t_{PLH}, t_{PHL}	$C_L = 50\text{pF}$	2	-	-	100	-	-	125	-	-	150	ns
			4.5	-	-	20	-	-	25	-	-	30	ns
		$C_L = 15\text{pF}$	5	-	8	-	-	-	-	-	-	-	ns
		$C_L = 50\text{pF}$	6	-	-	17	-	-	21	-	-	26	ns
Data to Outputs HC241	t_{PLH}, t_{PHL}	$C_L = 50\text{pF}$	2	-	-	110	-	-	140	-	-	165	ns
			4.5	-	-	22	-	-	28	-	-	33	ns
		$C_L = 15\text{pF}$	5	-	9	-	-	-	-	-	-	-	ns
		$C_L = 50\text{pF}$	6	-	-	19	-	-	24	-	-	28	ns
Data to Outputs HC244	t_{PLH}, t_{PHL}	$C_L = 50\text{pF}$	2	-	-	110	-	-	140	-	-	165	ns
			4.5	-	-	22	-	-	28	-	-	33	ns
		$C_L = 15\text{pF}$	5	-	9	-	-	-	-	-	-	-	ns
		$C_L = 50\text{pF}$	6	-	-	19	-	-	24	-	-	28	ns
Output Enable and Disable Time	t_{THL}, t_{TLH}	$C_L = 50\text{pF}$	2	-	-	150	-	-	190	-	-	225	ns
			4.5	-	-	30	-	-	38	-	-	45	ns
		5	-	12	-	-	-	-	-	-	-	-	ns
		6	-	-	26	-	-	33	-	-	38	ns	
Output Transition Time	t_{TLH}, t_{THL}	$C_L = 50\text{pF}$	2	-	-	60	-	-	75	-	-	90	ns
			4.5	-	-	12	-	-	15	-	-	18	ns
			6	-	-	10	-	-	13	-	-	15	ns
Input Capacitance	C_I	$C_L = 50\text{pF}$	-	10	-	10	-	-	10	-	-	10	pF
Three-State Output Capacitance	C_O	$C_L = 50\text{pF}$	-	-	-	20	-	-	20	-	-	20	pF
Power Dissipation Capacitance (Notes 5, 6)	C_{PD}	$C_L = 15\text{pF}$	5	-	38	-	-	-	-	-	-	-	pF
			5	-	34	-	-	-	-	-	-	-	pF
			5	-	46	-	-	-	-	-	-	-	pF
HCT TYPES													
Propagation Delay Data to Outputs HCT240	t_{PHL}, t_{PLH}	$C_L = 50\text{pF}$	4.5	-	-	22	-	-	28	-	-	33	ns
		$C_L = 15\text{pF}$	5	-	9	-	-	-	-	-	-	-	ns
Data to Outputs HCT241	t_{PHL}, t_{PLH}	$C_L = 50\text{pF}$	4.5	-	-	25	-	-	31	-	-	38	ns
		$C_L = 15\text{pF}$	5	-	10	-	-	-	-	-	-	-	ns
Data to Outputs HCT244	t_{PHL}, t_{PLH}	$C_L = 50\text{pF}$	4.5	-	-	25	-	-	31	-	-	38	ns
		$C_L = 15\text{pF}$	5	-	10	-	-	-	-	-	-	-	ns

CD74HC240, CD74HCT240, CD74HC241, CD74HCT241, CD74HC244, CD74HCT244

Switching Specifications $C_L = 50\text{pF}$, Input $t_r, t_f = 6\text{ns}$ (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	V_{CC} (V)	25°C			-40°C TO 85°C			-55°C TO 125°C			UNITS
				MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
Output Enable and Disable Times	t_{TLH}, t_{TLH}	$C_L = 50\text{pF}$	4.5	-	-	30	-	-	38	-	-	45	ns
Output Transition Time	t_{THL}, t_{TLH}	$C_L = 50\text{pF}$	4.5	-	-	12	-	-	15	-	-	18	ns
Input Capacitance	C_I	$C_L = 50\text{pF}$	-	10	-	10	-	-	10	-	-	10	pF
Power Dissipation Capacitance (Notes 5, 6)	C_{PD}												
HCT240		-	5	-	40	-	-	-	-	-	-	-	pF
HCT241		-	5	-	38	-	-	-	-	-	-	-	pF
HCT244		-	5	-	40	-	-	-	-	-	-	-	pF

NOTES:

- C_{PD} is used to determine the dynamic power consumption, per channel.
- $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$ where f_i = Input Frequency, f_O = Output Frequency, C_L = Output Load Capacitance, V_{CC} = Supply Voltage.

Test Circuits and Waveforms

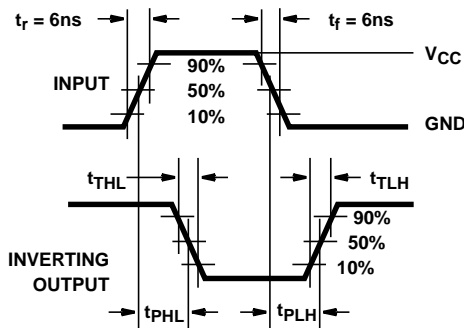


FIGURE 1. HC TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

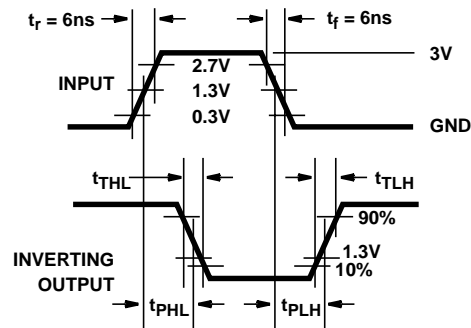


FIGURE 2. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

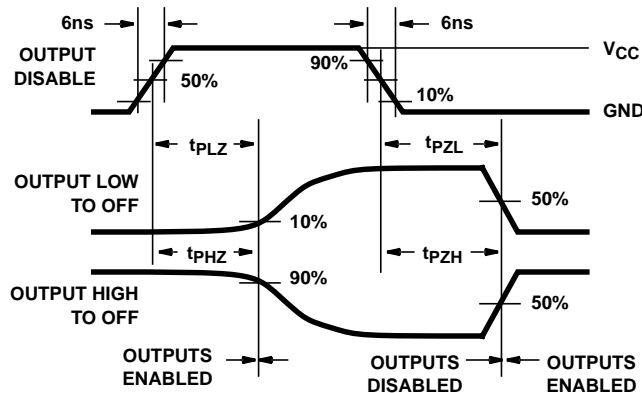
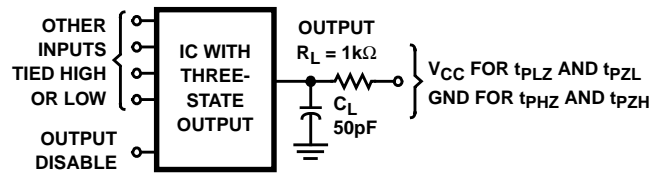


FIGURE 3. HC THREE-STATE PROPAGATION DELAY WAVEFORM



FIGURE 4. HCT THREE-STATE PROPAGATION DELAY WAVEFORM

Test Circuits and Waveforms (Continued)



NOTE: Open drain waveforms t_{pLZ} and t_{pZL} are the same as those for three-state shown on the left. The test circuit is Output $R_L = 1k\Omega$ to V_{CC} , $C_L = 50pF$.

FIGURE 5. HC AND HCT THREE-STATE PROPAGATION DELAY TEST CIRCUIT

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